

(1.00 mm) .0394"

PCIE-LP SERIES

PCI EXPRESS® LOW-PROFILE ASSEMBLY

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?PCIE-LP

Insulator Material:

Black Nylon LCP

Contact:

Phosphor Bronze

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

2.1 A per pin

(2 adjacent pins powered)

Operating Temp:

-55 °C to +125 °C

RoHS Compliant:

Yes

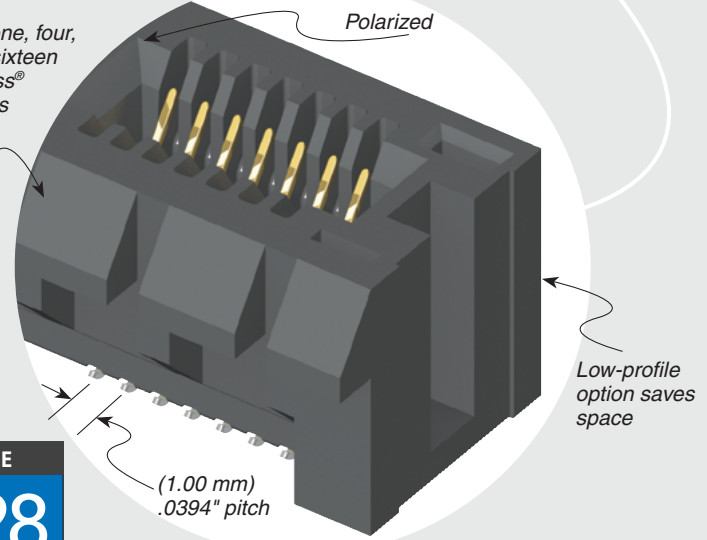
Card Mates:

(1.60 mm) .062" card

Cable Mates:

PCIEC

Supports one, four, eight and sixteen PCI Express® GEN 4 links



Low-profile option saves space

PROCESSING

Lead-Free Solderable:

Yes

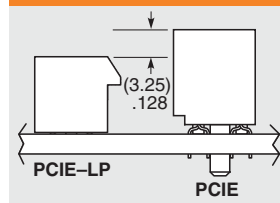
HIGH-SPEED CHANNEL PERFORMANCE

PCIE-LP

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

28
Gbps

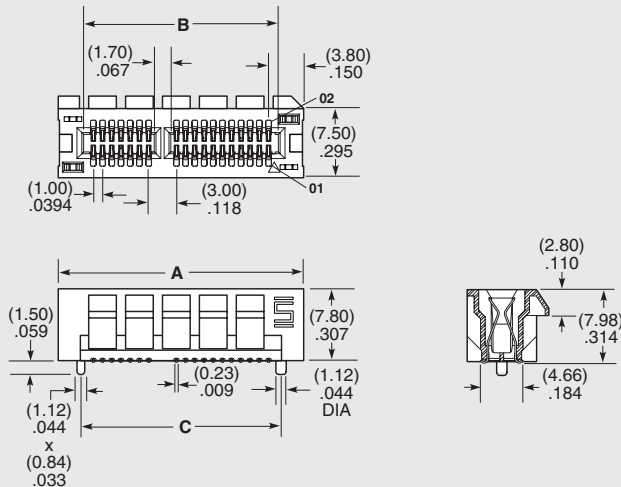
APPLICATION



PCIE	LP	NO. OF LANES	01	PLATING OPTION	DV	A	OPTION	PACKAGING
-01, -04, -08, -16				-F = Gold flash on contact, Matte Tin on tail	-S = 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail	-WT = Weld Tab	-K = Polyimide film Pick & Place Pad	-TR = Tape & Reel (Available with -01, -04 -08 lanes only)

OTHER SOLUTIONS

- Press-fit tails in development



PCIE-LP-01-01-X-DV-A SHOWN

NO. OF LANES	A	B	C
-01	(26.60) 1.047	(21.00) .827	(21.70) .854
-04	(40.60) 1.598	(35.00) 1.378	(35.70) 1.406
-08	(57.60) 2.268	(52.00) 2.047	(52.70) 2.075
-16	(90.60) 3.567	(85.00) 3.346	(85.70) 3.374

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Note:

Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.